

## Materials Declaration

<b>Package</b>	LFCSP - Punched
<b>Body Size</b>	4 X 4 X 0.85 (no EP)
<b>LeadCount</b>	16
<b>Option</b>	Pb-free

Molding Compound			
Substance	% of Compound	Weight (g)	PPM
Silica	86.91	1.26 E-02	301546
Epoxy & Phenol Resin	12.78	1.85 E-03	44342
Carbon black	0.31	4.50 E-05	1076
Subtotal	100.00	1.45 E-02	346963

Leadframe			
Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	2.21 E-02	528067
Iron	2.35	5.32 E-04	12728
Zinc	0.12	2.72 E-05	650
Phosphorus	0.03	6.80 E-06	162
Subtotal	100	2.27 E-02	541607

Internal Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Silver	100	5.00 E-04	11956

External Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Tin	100	7.30 E-04	17456

Bond Wires			
Substance	% of Wire	Weight (g)	PPM
Gold	99.99	3.60 E-04	8608

Chip			
Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.40 E-03	57389

Die Attach			
Substance	% of Die Attach	Weight (g)	PPM
Silver	73.40	4.92 E-04	11759
Epoxy Resin	18.35	1.23 E-04	2940
Metal oxide	2.75	1.84 E-05	441
Curing and hardening agent	2.75	1.84 E-05	441
Gamma Butyrolactone	2.75	1.84 E-05	441
Subtotal	100.00	6.70 E-04	16021

Package Totals	
Weight (g)	PPM
4.18 E-02	1000000

Molding Compound		
Substance	PPM	Method
Lead	Not Detected	Draft IEC62321. ICP-OES.
Cadmium	Not Detected	Draft IEC62321. ICP-OES.
Mercury	Not Detected	Draft IEC62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC62321. GC-MSD.

Die Attach Paste		
Substance	PPM	Method
Lead	Not Detected	Draft IEC62321. ICP-OES.
Cadmium	Not Detected	Draft IEC62321. ICP-OES.
Mercury	Not Detected	Draft IEC62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC62321. GC-MSD.

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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